High-Speed 56⁺Gbps BGA Mezzanine Connectors

IT8 Series



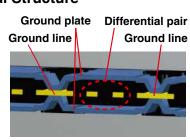
Overview

The IT8 mezzanine connector system was developed to enable 56Gbps performance with the highest signal density in the market, featuring Quasi-Coaxial Structure and Polarity-Swap FEXT cancelling technology.

IT8 delivers the most reliable and flexible solution for your current and future needs to design high speed systems.

■Quasi-Coaxial Structure



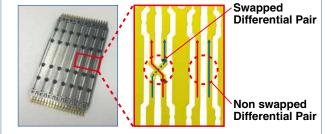


Patented

■Mechanical Features

- Stack heights:
 - -10 to 13mm (Two-piece type)
 - -14 to 46mm (Three-piece type)
- Number of Contacts: 120, 192, 288 signals
- Multiple mating capability
 - Floating amount : +/-0.2mm in X,Y
- Mating alignment: +/-1.5mm
- 1.0×5.5mm BGA interface optimizes routing and SI performance
- BGA attachment with "Pin in Ball" ensures reliable solder joints with high **SMT processing yields**
- Excellent reflow solderability with superior BGA coplanarity control
- Compatible with double-sided and inverted reflow soldering

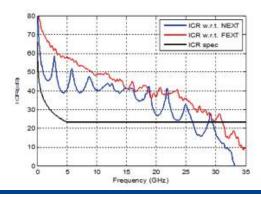
■Polarity-Swap FEXT cancelling technology



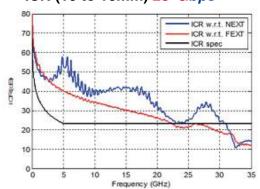
■Signal Integrity Features

- SI capability
 - -56⁺Gbps (18 to 46mm), 28⁺Gbps (10 to 16mm)
 - -92ohm impedance (suitable for both 100ohm & 85ohm system)
- Unique Polarity-Swap FEXT cancelling technology
- Quasi-Coaxial Structure to prevent noise emission to adjacent lines
- Insertion loss to Crosstalk Ratio (ICR)

ICR (18 to 46mm) 56+Gbps



ICR (10 to 16mm) 28+Gbps

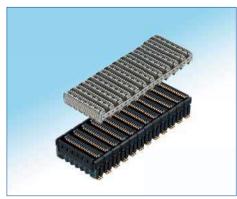


■Stacking Height Variations

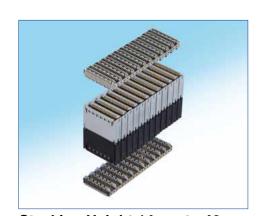
	Tw	o-pie	ce ty	ре		Three-piece type															
Stacking Height Contact Position	10 mm	11 mm	12 mm	13 mm	14 mm	15 mm	16 mm	17 mm	18 mm	19 mm	20 mm	21 mm	22 mm	23 mm	24 mm	25 mm	26 mm	27 mm	28 mm	29 mm	30 mm
120	~	~	1	~	~	~	~	*	~	1	~	*	~	~	~	~	~	~	~	1	~
192	1	~	1	1	1	1	~	*	~	~	~	*	~	1	~	~	~	~	~	~	~
288	1	~	1	1	1	~	~	*	~	~	~	*	~	~	1	~	~	~	~	~	~

		Three-piece type														
Stacking Height Contact Position	31 mm	32 mm	33 mm	34 mm	35 mm	36 mm	37 mm	38 mm	39 mm	40 mm	41 mm	42 mm	43 mm	44 mm	45 mm	46 mm
120	*	1	~	/	/	1	1	1	~	/	~	1	~	~	/	~
192	*	1	1	1	1	1	1	1	1	/	1	1	1	1	/	~
288	*	1	1	1	1	1	1	1	1	/	1	1	1	1	/	~

✓ Available / * Please contact us



Stacking Height 10mm to 13mm Two-piece type



Stacking Height 14mm to 46mm Three-piece type

■Product Specifications

	Operating Temperature Range: -55°C to +85°C	Storage Temperature Range : -10°C to +60°C
Rating	Voltage Rating : 50Vrms	Operating Humidity Range: For relative humidity,
	Current Rating: 0.5A / pin (Signal)	90% max (No dew condensation is permitted)

Item	Specification	Conditions
1. Contact Resistance (Note1)	50mΩ MAX (Height : 10 to 19mm) 60mΩ MAX (Height : 20 to 29mm) 70mΩ MAX (Height : 30 to 39mm) 80mΩ MAX (Height : 40 to 46mm)	100mA
2. Insulation Resistance	1000MΩ min.	100V DC
3. Withstanding Voltage	No flashover or insulation breakdown	150V duty for 60 seconds
4. Mechanical Operation (Mating/Un-mating)	1) Contact resistance change : $20m\Omega$ or less 2) No damage, crack or loose part	100 cycles
5. Random Vibration	 No electrical discontinuity of 1 µs or more No damage, crack or loose part 	Frequency : 50 to 2000Hz ; power spectrum density : $0.1G^2/Hz$ for 120 minutes in three directions
Cyclic Temperature and Humidity	1) Contact resistance change : $20m\Omega$ or less 2) No damage, crack or loose part	$25^{\circ}\text{C},80\%$ RH : 60 min dwell time, 30 min ramp time $65^{\circ}\text{C},50\%$ RH : 60 min dwell time under 24 cycles

Note1: The value of contact resistance includes the bulk resistance.

■Materials / Finish

•Receptacle

Part	Material	Finish	Remarks
Housing	PPS	Black	UL94V-0
Blade	LCP	Black	UL94V-0
Contact	Copper Alloy	Contact Area : Gold (0.76 μ m min) over Nickel (1.27 μ m min) Other : Nickel (1.27 μ m min)	_
Ground Shield	Stainless Steel		_
Ground Shield	Stainless Steel		_
Retention Peg	Copper Alloy	Gold (0.03 μ m min) over Nickel (1.0 μ m min)	_
Solder Ball	Tin (Pb-Free)	Sn(96.5)-Ag(3)-Cu(0.5)	_
Pick Up Tape	Heat Resistant Tape	Polyamide	_
Tray	HIPS	Black	_

Interposer

Part	Material	Finish	Remarks
Housing (Detachable Side)	PPS	Gray	UL94V-0
Housing (Mounting Side)	PPS	Black	UL94V-0
Guide Plate	Stainless Steel		
Blade	LCP	Black	UL94V-0
Contact	Copper Alloy	Contact Area : Gold (0.76 μ m min) over Nickel (1.27 μ m min) Other : Nickel (1.27 μ m min)	
Ground Shield	Stainless Steel		
Ground Shield	Stainless Steel		
Tray	HIPS	Not shown in the customer drawing	

●Plug

Part	Material	Finish	Remarks
Ground Shield	Copper Alloy	Nickel (1.27 µm min)	
Housing	LCP	Black or Gray	UL94V-0
Contact	Copper Alloy	Contact Area : Gold (0.76 μ m min) over Nickel (1.27 μ m min) Other : Nickel (1.27 μ m min)	
Solder Ball	Tin	Sn(96.5)-Ag(3)-Cu(0.5)	
Pick Up Cap	PA-M	Black	UL94V-0
Tray	HIPS		

■Product Number Structure

Refer to the chart below when determining the product specifications from the product number. Please select from the product numbers listed in this catalog when placing orders.

Plug Mounting Side

•Interposer

Plug Detachable Side

•Mounting Receptacle

1 Series Name: IT8

No Further Designation

2 Connector Type

IT8M-xxxP-BGA: Mounting Plug IT8D-xxxP-BGA : Detachable Plug IT8MB -xxxS-BGA: Mounting Receptacle

3 Signal Contact Positions

120, 192, 288

4 Connector Gender

S: Female (Receptacle or Interposer)

P: Male (Plug)

6 BGA : Ball Grid Array

No Further Designation

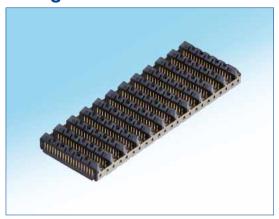
6 Stacking Height (mm)

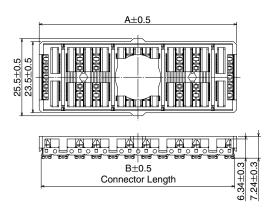
Mounting Plug: 0, 1 Detachable Plug: 0, 1 Mounting Receptacle: 10, 12

Interposer: 14, 18, 22, 25, 28, 32, 35, 38, 41, 44

> Two-piece type; 6 Mounting Receptacle + 6 Detachable Plug

■Plug

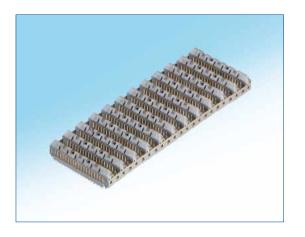


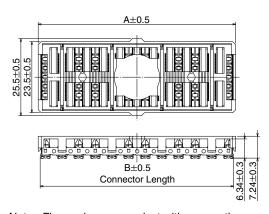


Note: Figure shows a product with a mounting cap. Products are shipped with mounting caps attached.

Unit: mm

Signal contact No.	Туре	Part No.	HRS No.	А	В	
120 (+70 ground)		IT8M-120P-BGA-0H	636-3001-9 00	26.8	25.5	
		IT8M-120P-BGA-1H	636-3100-0 00	26.8	25.5	
192 (+112 ground)	Three piece type	IT8M-192P-BGA-0H	636-3002-1 00	43.3	42	
	Mounting side	IT8M-192P-BGA-1H	636-3101-3 00	43.3	42	
288 (+168 ground)		IT8M-288P-BGA-0H	636-3003-4 00	65.3	64	
288 (+108 ground)		IT8M-288P-BGA-1H	636-3102-6 00	05.5	04	





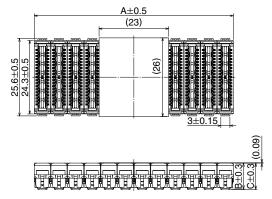
Note: Figure shows a product with a mounting cap. Products are shipped with mounting caps attached.

Unit: mm

Signal contact No.	Туре	Part No.	HRS No.	Α	В	
120 (+70 ground)		IT8D-120P-BGA-0H	636-3200-5 00	26.8	25.5	
120 (+70 glouliu)		IT8D-120P-BGA-1H	636-3300-0 00	20.6	25.5	
192 (+112 ground)	Two / Three piece type	IT8D-192P-BGA-0H	636-3201-8 00	43.3	42	
192 (+112 ground)	Detachable side	IT8D-192P-BGA-1H	636-3301-2 00	43.3	42	
288 (+168 ground)		IT8D-288P-BGA-0H	636-3202-0 00	65.3	64	
266 (+166 ground)		IT8D-288P-BGA-1H	636-3302-5 00	05.5	64	

■Receptacle





Note: Figure shows a product with a mounting tape. Products are shipped with mounting tape attached.

Unit: mm

Signal contact No.	Туре	Part No.	HRS No.	Α	В	С
120 (+70 ground)		IT8MB-120S-BGA-10H	636-3804-0 00	27.3	8.6	8.75
192 (+112 ground)		IT8MB-192S-BGA-10H	636-3805-0 00	43.8	8.6	8.75
288 (+168 ground)	Two piece	IT8MB-288S-BGA-10H	636-3806-0 00	65.8	8.6	8.75
120 (+70 ground)	type	IT8MB-120S-BGA-12H	636-3906-0 00	27.3	8.6	10.75
192 (+112 ground)		IT8MB-192S-BGA-12H	636-3905-0 00	43.8	8.6	10.75
288 (+168 ground)		IT8MB-288S-BGA-12H	636-3907-0 00	65.8	8.6	10.75

■Interposer



25.6			
¥	-		
-			
		П	

Unit: mm

Signal contact No.	Part No.	HRS No.	Α	В
	IT8-120S-14H	636-3526-0 00		11.4
	IT8-120S-18H	636-3529-0 00		15.4
	IT8-120S-22H	636-3506-0 00		19.4
	IT8-120S-25H	636-3503-0 00		22.4
120	IT8-120S-28H	636-3509-0 00	27.44	25.4
(+70 ground)	IT8-120S-32H	636-3512-0 00	27.44	29.4
	IT8-120S-35H	636-3500-9 00		32.4
	IT8-120S-38H	636-3517-0 00		35.4
	IT8-120S-41H	636-3520-0 00		38.4
	IT8-120S-44H	636-3523-0 00		41.4

Signal contact | Bort No | HPS No

No.	Part No.	HRS No.	A	В
	IT8-288S-14H	636-3528-0 00		11.4
	IT8-288S-18H	636-3531-0 00		15.4
	IT8-288S-22H	636-3508-0 00		19.4
	IT8-288S-25H	636-3505-0 00		22.4
288	IT8-288S-28H	636-3511-0 00	65.94	25.4
(+168 ground)	IT8-288S-32H	636-3514-0 00	05.94	29.4
	IT8-288S-35H	636-3502-4 00		32.4
	IT8-288S-38H	636-3519-0 00		35.4
	IT8-288S-41H	636-3522-0 00		38.4
	IT8-288S-44H	636-3525-0 00		41.4

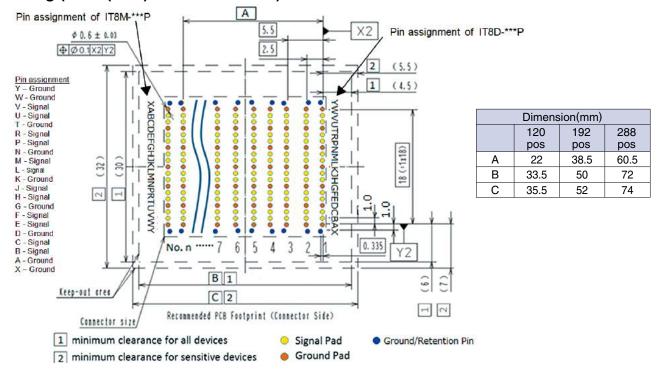
Unit: mm

Signal contact No.	Part No.	HRS No.	Α	В
	IT8-192S-14H	636-3527-0 00		11.4
	IT8-192S-18H	636-3530-0 00		15.4
	IT8-192S-22H	636-3507-0 00		19.4
	IT8-192S-25H	636-3504-0 00		22.4
192	IT8-192S-28H	636-3510-0 00	43.94	25.4
(+112 ground)	IT8-192S-32H	636-3513-0 00	43.94	29.4
	IT8-192S-35H	636-3501-1 00		32.4
	IT8-192S-38H	636-3518-0 00		35.4
	IT8-192S-41H	636-3521-0 00		38.4
	IT8-192S-44H	636-3524-0 00		41.4

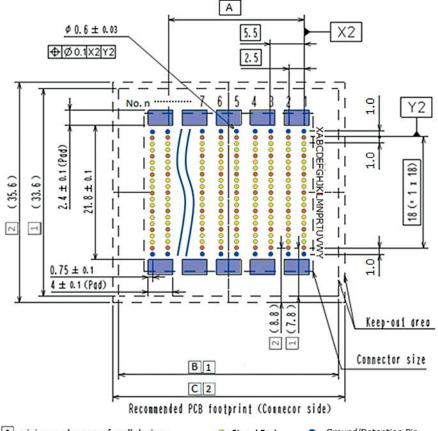
Unit: mm

Recommended Land Pattern Dimension of PCB (Metal mask thickness: t=0.127 to 0.15mm)

◆Plug (IT8M (or D) -***P-BGA-*H)



●Receptacle (IT8MB-***S-BGA-**H)



Dimension(mm)			
	120	192	288
	pos	pos	pos
Α	22	38.5	60.5
В	35.5	52	74
С	37.5	54	76

minimum clearance for all devices
minimum clearance for sensitive devices

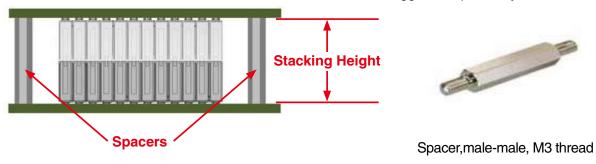
Signal PadGround Pad

Ground/Retention Pin
 Floating/Retention Peg

♦ Spacers

Spacers are required to support the PWB's and protect the BGA solder joints.

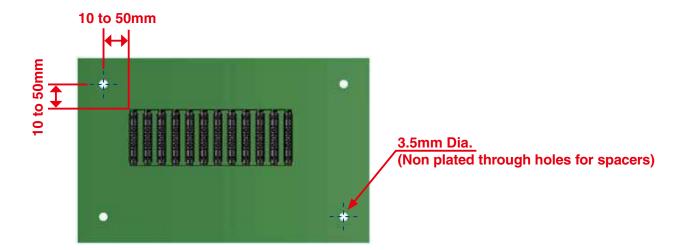
Suggested spacer style is shown below:



The spacer heights must correspond to the stacking heights as shown below.

Stacking Height	Spacer Height	
XXmm	XX +/-0.127mm	

Note: XX is the value of stacking height.



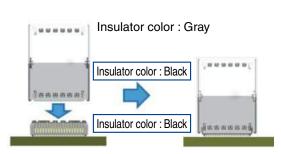
Four spacers located rectangularly or simmiler are required. Spacers should be located 10 to 50mm from the corners of the plugs or receptacles to preventexcessive mechanical loading on the interconnections.

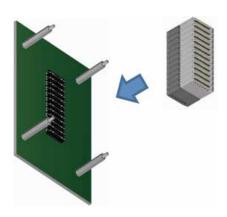
If assembly will be subjected to vibration, spacers should be located to prevent resonance, and additional spacers may be required.

◆Interposer Installation

Mate black side of the interposer with the black mounting plug, otherwise signal pin-out will change and cause a system error.

The interposer snaps onto the mounting plug as shown below.

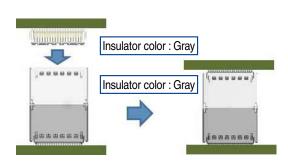


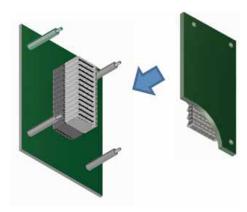


● Daughter Card Installation

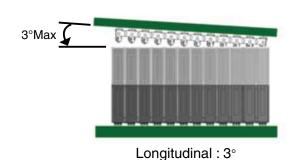
Insulator color of the datachable plug is gray, and the detachable plug must mate with the gray side of the interposer.

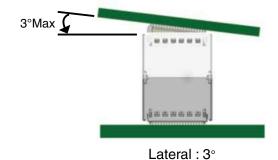
The spacers should be installed prior to the operation. The detachable plug shall be aligned with the interposer and pressed on as shown below.





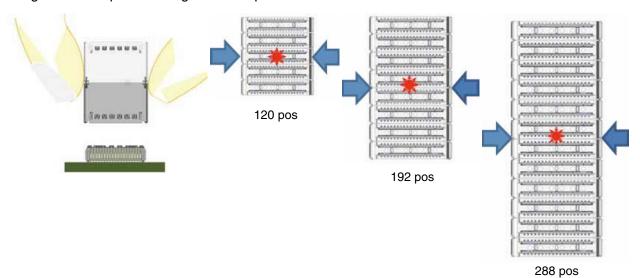
In mating operation, 0° for following angles are preferred. In case keeping 0° is difficult, following maximum angles should not be exceeded during manual installation of the daughter card as shown below:



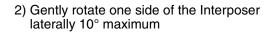


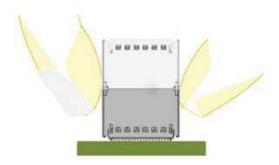
◆Interposer Removal

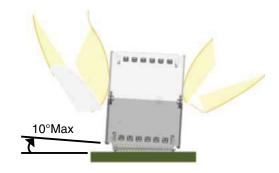
The removal of interposer shall be 5 times max. For removal, hold the Interposer on the walls as shown below. Also, please grab the walls close to the grabity center of the interposer to prevent tilting of the interposer during removal operation.



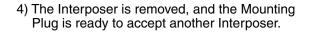
1) Hold the Interposer on the walls.

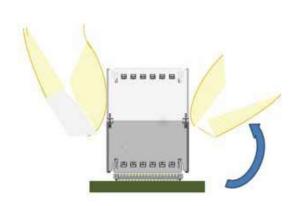


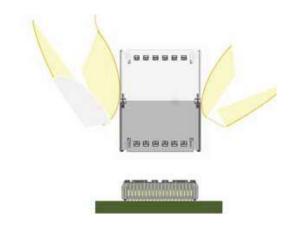




3) While gently rotating, pull up on other side of the Interposer.





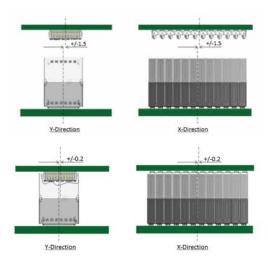


Mating Self Alignment

IT8 connector system have wide guiding taper for self alignment so that IT8 accept ±1.5mm tolerance in the both X-direction and Y-direction

Mating Tolerance

Due to its unique floating structure design, the IT8 connector system can accept mating tolerances of up to ±0.2mm tolerance in the both X-direction and Y-direction for multiple connector use.

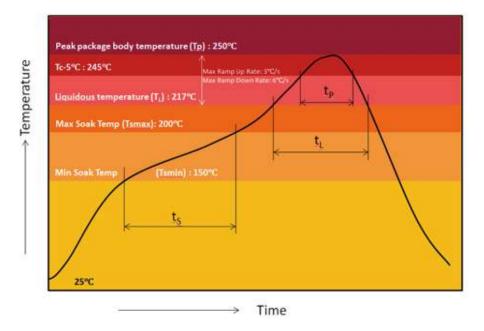


Assembly Relow Soldering Profile

Profile Feature	Condition	Note
Preheat/Soak Temperature Min (Tsmin) Temperature Max (Tsmax) Time (ts) from (Tsmin to Tsmax)	150°C 200°C 60 to 120 seconds	Soak requirements determined by board design, oven capability, and paste activation requirements. Caution- "oversoaking" may exhaust flux and affect soldering.
Ramp-up rate (TL to Tp)	3°C/second max.	Other components may limit ramp rate to 2°C/sec.
Liquidous temperature (TL) Time (tL) maintained above TL	217°C 60 to 150 seconds	Shorter t _∟ may require higher peak temperature.
Peak package body temperature (Tp)	250°C max.	Cooler peak temperatures may require longer t _L . For users Tp must not exceed the Classification temp (Tc) of 250°C.
Time (tp)* within 5°C of the specified classification temperature (Tc)	30 seconds max.	
Ramp-down rate (Tp to TL)	6°C/second max.	
Package Body Exposure Limit at Maximum Temperature	5 seconds	Adjust profile if maximum exposure limits approached or exceeded.

All temperatures refer to the center of the connector body, measured on the connector body surface that is facing up during assembly reflow.

Reflow profiles in this document are basically according to IPC/JEDEC J-STD-020D. 1 and are for preconditioning. Actual board assembly profiles should be developed based on specific process needs and board designs and should not exceed the parameters in upper Table.



Different solder pastes have different thermal performance characteristics. Consult with paste manufacturer for optimum profile setting.

● Packaging Information

Please order per box with its Minimum Order Quantity (MOQ) of connectors contained. The number for each configuration is shown below.

(Receptacle) IT8MB-***S-BGA-**H (Plug) IT8M (or D) -***P-BGA-*H

Part No.	Quantity per Tray	Quantity per Box (3 trays + 1 rid *1)
IT8*-120P (or S) -BGA-**H	36pcs	108pcs
IT8*-192P (or S) -BGA-**H	24pcs	72pcs
IT8*-288P (or S) -BGA-**H	16pcs	48pcs

*1 : The lid is an empty Tray or a specialized lid.

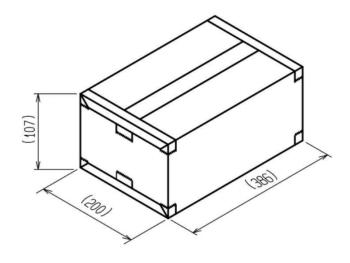
(Interposer) IT8-***S-**H

No. of Contacts	Quantity per Tray
120pos	36pcs
192pos	24pcs
288pos	16pcs

No. of Contacts	Quantity per Box (28 to 44H type) (1 trays + 1 rid *2)	Quantity per Box (14 to 25H type) (2 trays + 1 rid *2)
120pos	36pcs	72pcs
192pos	24pcs	48pcs
288pos	16pcs	32pcs

*2: The lid is a specialized lid.

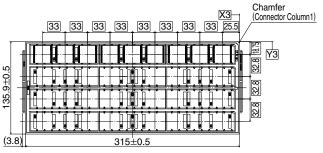
● Final Appearance of Packaging



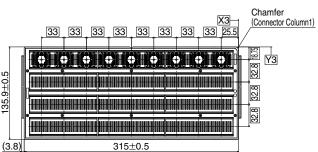
◆Tray dimensions

•Receptacle

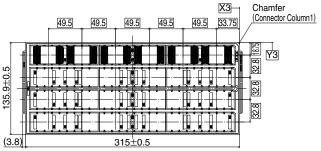
●Plug



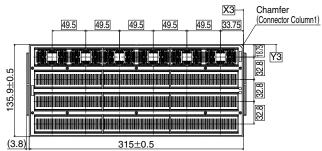
IT8MB-120S-BGA-**H



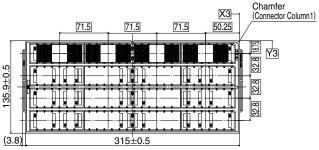
IT8M (or D) -120P-BGA-*H



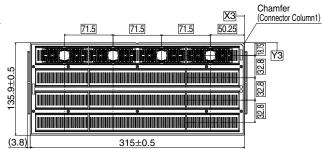
IT8MB-192S-BGA-**H



IT8M (or D) -192P-BGA-*H



IT8MB-288S-BGA-**H



IT8M (or D) -288P-BGA-*H

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